Call for Abstracts
The NordPac Conference 2019
June 11 – 13 at Technical University of Denmark, Lyngby, Denmark
Jointly arranged by IMAPS Nordic and IEEE EPS Nordic

We are proud to announce that the 2019 NordPac conference will be held in Denmark. The event brand NordPac was introduced in Gothenburg in 2017 as a collaboration between IMAPS Nordic and IEEE Electronics Packaging Society (EPS) Nordic. The conference will take place at Technical University of Denmark, Lyngby, a few kilometres north of Copenhagen.

You are welcome to submit an abstract and suggestion for a paper to the NordPac Conference 2019. For instructions on how to submit your abstract, please see http://nordpac.org. The deadline for abstract submission is Friday 22nd of March 2019.

For students we have the possibility to have papers classified as Reviewed and published in both IEEE Xplore and IMAPS North America IMAPSource, http://ieeexplore.ieee.org/ and http://www.imapsource.

The deadline for the final paper will be in May 22nd, 2019, but if you want your paper to be reviewed deadline is May 1st. Late papers are not published.

As part of the annual IMAPS Nordic conference, PhD and Master Students are especially encouraged to submit an abstract. For this we have set up a Review process for those who need reviewed and published papers. This is a great opportunity to interact with the industrial and academic community at an international level (coming from inside and outside the Nordic countries).

Proposed topics of microelectronics and packaging include:

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<th>Printed, flexible electronics</th>
<th>Medical electronics</th>
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<td>Unique materials, PTF and ACF</td>
<td>OPTO-ELECTRONICAL and LED</td>
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<td>High temperature electronics, harsh environment</td>
<td>Sensor integration &amp; applications</td>
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<td>3D Advanced interconnect, advanced packaging</td>
<td>Wearable electronics</td>
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<td>Ceramics: thick film, copper plated, DBC, LTCC</td>
<td>Reliability assessments, SPC and FMEA</td>
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For the latest information about the conference and the exhibition, visit our homepage at http://nordpac.org/ or send e-mail to info@nordpac.org or to the Exhibition Host at exhibit@nordpac.org.

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IEEE EPT Nordic

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